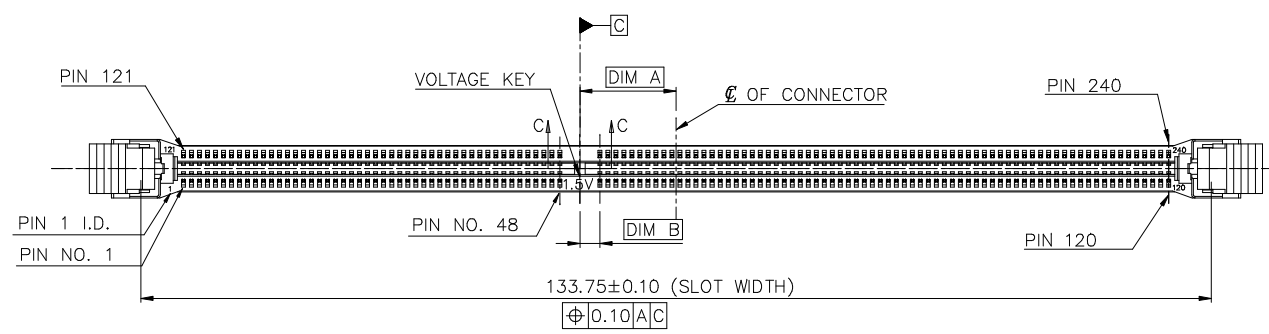
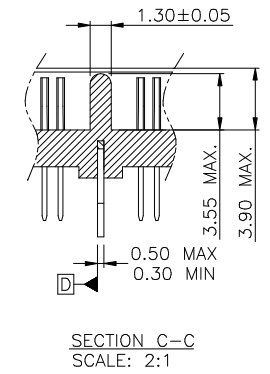
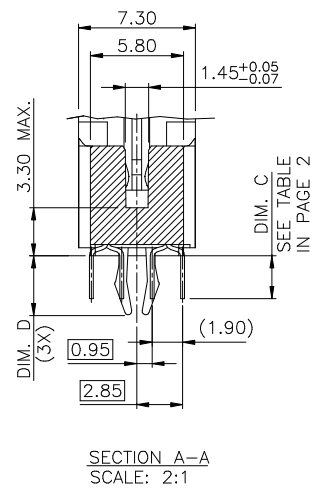
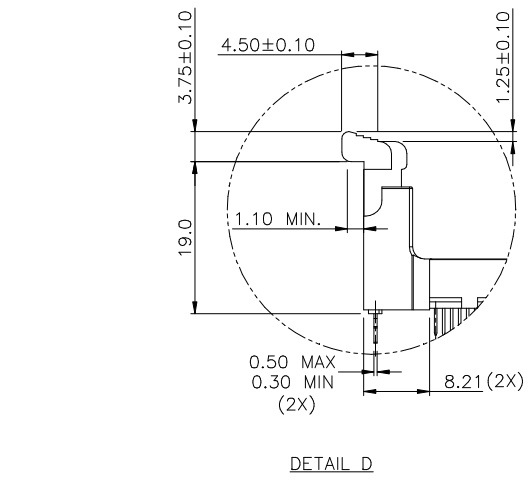
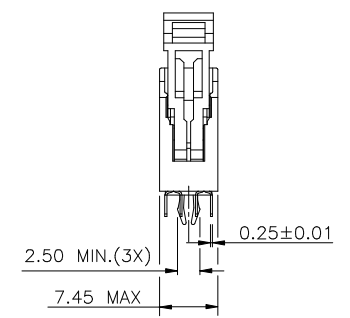
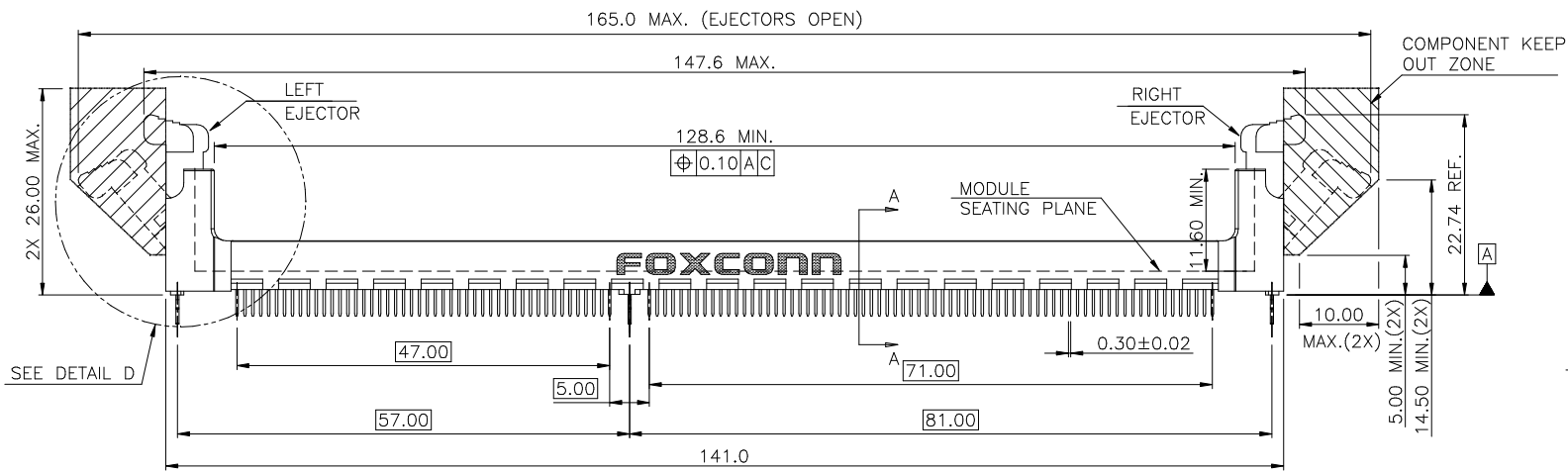


REV.	ECN.	NO.	APPD.
A	BC-13-0088033		Davy Bu 12/18'13



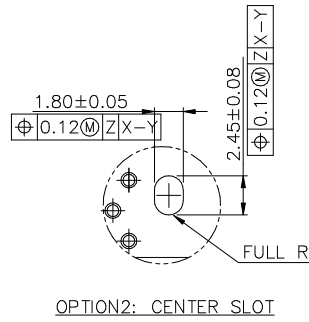
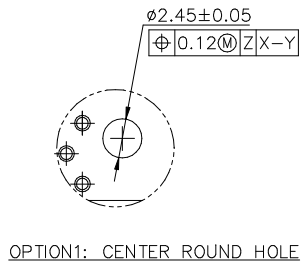
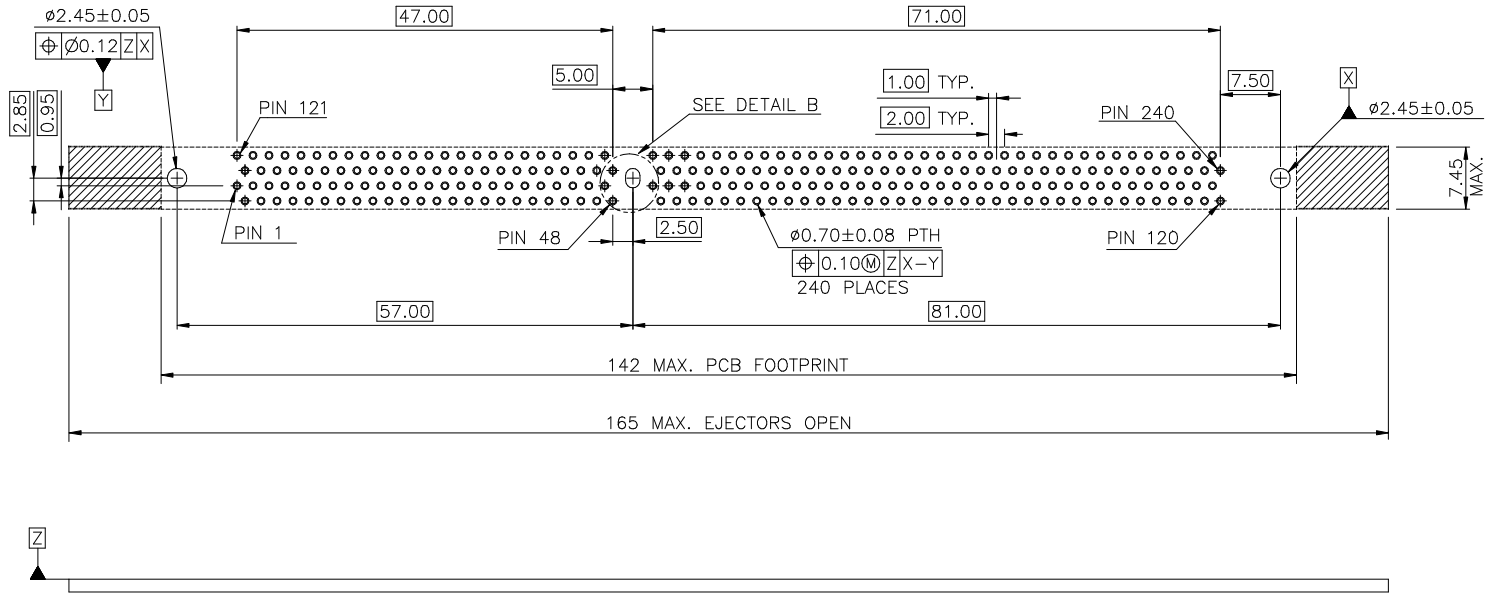
NOTES: UNLESS OTHERWISE SPECIFIED:  
 1. ALL DIMENSIONS ARE IN MILLIMETER.  
 2. INTERPRET DRAWINGS PER ASME Y14.5M-1994.



X.±	X.±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.x± 0.25	.x±	MAT'L		DDR III DIMM, 240 P 1.00mm PITCH	
.xx± 0.15	.xx±	FINISH		PART NO. (INTENDED USE)	TITLE:
.xxx±	.xxx±	Q'TY		ATH40**-H9*E-4*	CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: Davy Bu 12/18'13	DWG No.: 317-0000-2067
				CHKD: Arthur Niu 12/18'13	SCALE SHEET REV.
				DR: X.W Wang 12/18'13	N/A 1/4 A

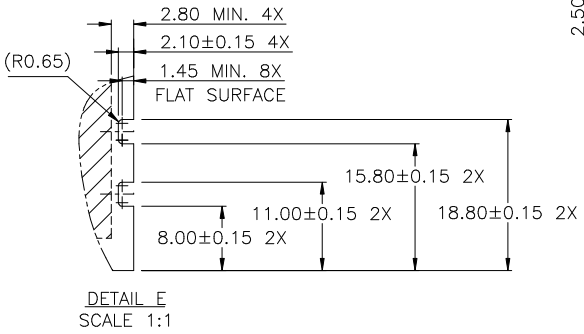
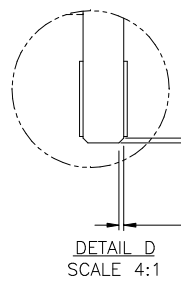
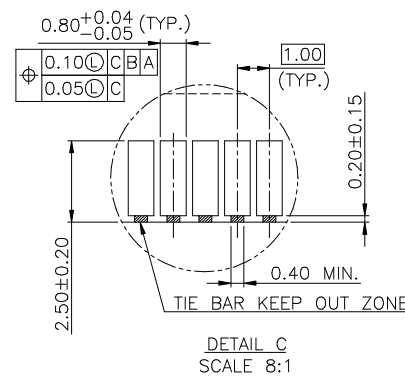
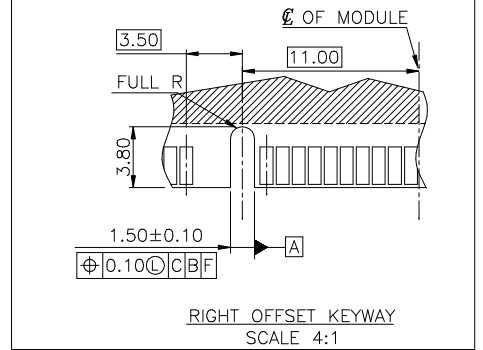
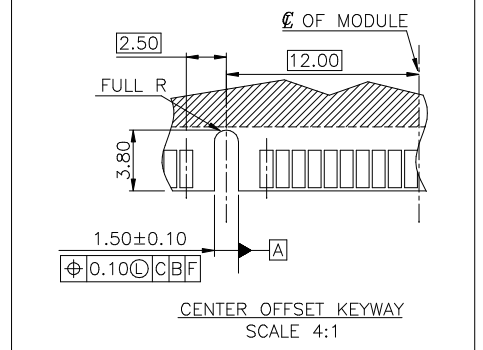
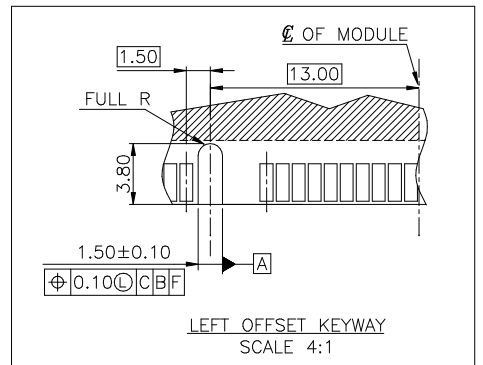
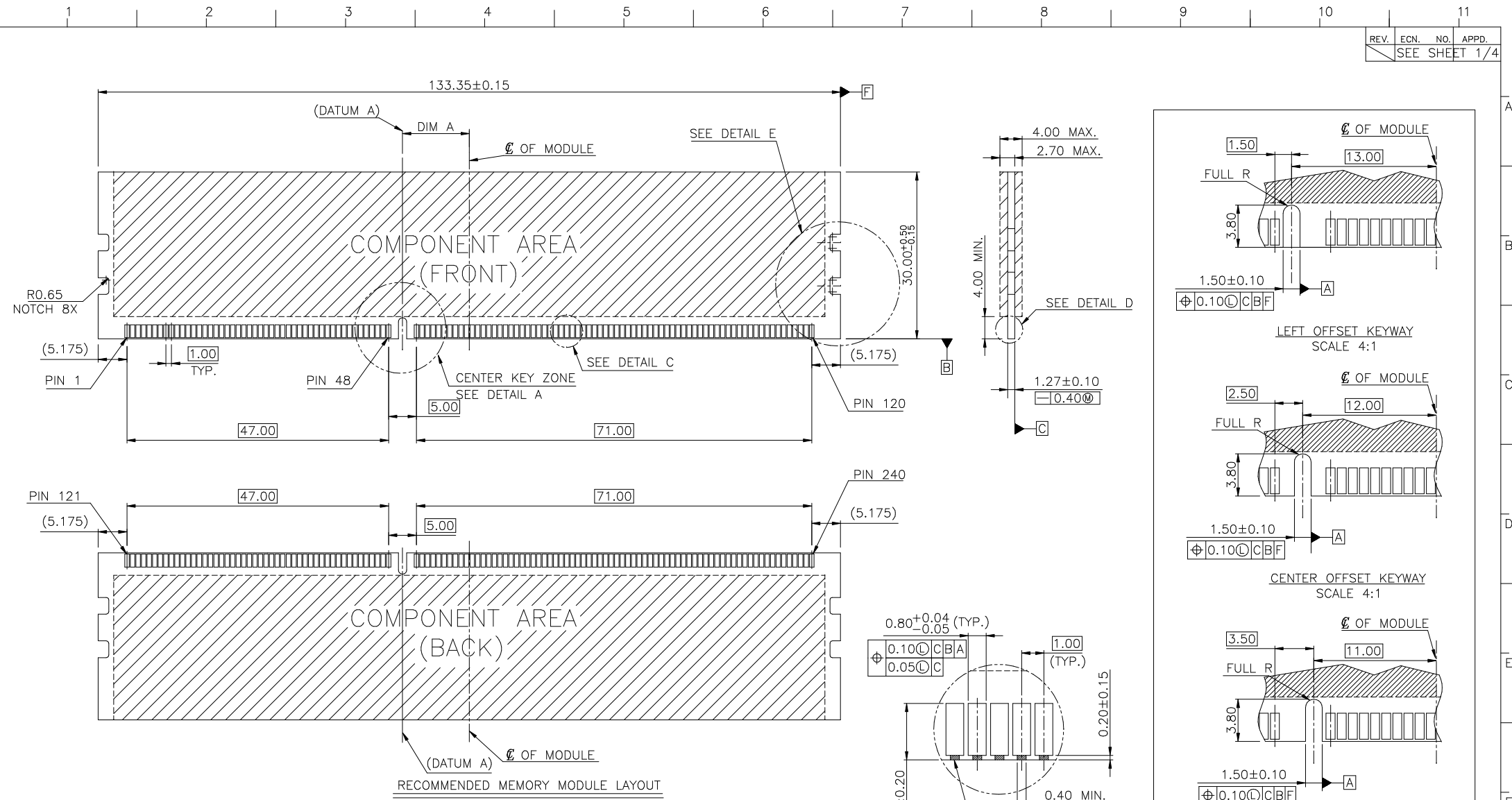
PART NUMBER	NO. OF POSITION	VOLTAGE MARKING	KEY POSITION	DIM. A	DIM. B	DIM. C CONTACT TAIL	DIM. D METAL BOARD LOCK
ATH401*-H9*E-4*	240	1.5V	CENTER OFFSET	12.00	2.50	2.67±0.25 FOR 1.57 (.062") PCB THICKNESS	3.78±0.25 FOR 1.57 (.062") PCB THICKNESS
ATH400*-H9*E-4*	240	1.5V	CENTER OFFSET	12.00	2.50	3.18±0.25 FOR 2.36 (.093") PCB THICKNESS	4.57±0.25 FOR 2.36 (.093") PCB THICKNESS

REV.	ECN.	NO.	APPD.
SEE SHEET 1/4			



DETAIL B

x.±	x.±	UNITS	mm	NAME(INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.x± 0.25	.x±	MAT'L		DDR III DIMM, 240 P 1.00mm PITCH	
.xx± 0.15	.xx±	FINISH		PART NO.(INTENDED USE)	TITLE:
.xxx±	.xxx±	Q'TY		ATH40*-H9*E-4*	CUSTOMER DRAWING
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				Davy Bu 12/18'13	317-0000-2067
				CHKD:	SCALE SHEET REV.
				Arthur Niu 12/18'13	N/A 2/4 A
				DR: X.W Wang 12/18'13	



x.±	x.±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN</b>
.x± 0.25	.x±	MAT'L		DDR III DIMM, 240 P 1.00mm PITCH	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.xx± 0.15	.xx±	FINISH		PART NO. (INTENDED USE)	TITLE:
.xxx±	.xxx±	Q'TY		ATH40**-H9*E-4*	CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD:	DWG NO.:
				Davy Bu 12/18'13	317-0000-2067
				CHKD:	SCALE SHEET REV.
				Arthur Niu 12/18'13	N/A 3/4 A
				DR: X.W Wang 12/18'13	

# SPECIFICATION:

## 1. PHYSICAL:

### 1-1. HOUSING:

HIGH TEMPERATURE THERMOPLASTIC, NYLON, UL 94V-0,  
COLOR: SEE PRODUCT NOMENCLATURE

### 1-2. CONTACT:

COPPER ALLOY, NICKEL PLATING OVERALL, THICKNESS 50  $\mu$ " MIN.,  
TIN LEAD FREE PLATING, THICKNESS 100  $\mu$ " MIN. AT TAILS,  
GOLD PLATING AT CONTACT AREA. THICKNESS REFER TO  
PRODUCT NOMENCLATURE.

### 1-3. EJECTOR:

THERMOPLASTIC, UL 94V-0, COLOR: SEE PRODUCT NOMENCLATURE.

### 1-4. METAL BOARD LOCK: COPPER ALLOY.

## 2. ELECTRICAL CHARACTERISTICS:

2-1. CONTACT CURRENT RATING: 0.75 AMPS MAX.

2-2. INSULATION RESISTANCE: 1 MEGOHMS MIN. AT 500 VDC.

2-3. DIELECTRIC WITHSTANDING VOLTAGE: 500 VDC AT SEA LEVEL.

2-4. LOW LEVEL CONTACT RESISTANCE (DRY CIRCUIT):  
INITIAL: 10 MILLIOHMS MAX.

FINAL: NO CHANGE GREATER THAN 10 MILLIOHMS MAX.  
AFTER FULL ENVIRONMENTAL TESTING.

## 3. MECHANICAL CHARACTERISTICS:

3-1. CONTACT RETENTION FORCE: 0.30 KG. (0.66 LBS) MIN. PER PIN.

3-2. DURABILITY: 25 CYCLES.

3-3. INSERTION FORCE OF CONNECTOR INTO PCB (WITH THREE BOARD  
LOCKS): 7.6 KG (16.75 LBS) MAX.

3-4. INSERTION FORCE OF MODULE INTO CONNECTOR 10.88 KG (24 LBS) MAX.

3-5. UNMATING FORCE (PER CONTACT PAIR): 14 g MIN.

## 4. ENVIRONMENTAL CHARACTERISTICS:

4-1. SOLDERABILITY: PASSED PER EIA-364-52, CLASS 2, CATEGORY 3.

WAVE SOLDER REFERENCE PROFILE:

PREHEATING TEMPERATURE 25~140 Degree & 80s Min. SOLDERING TEMPERATURE 260 Degree & 5s.

4-2. VIBRATION: PASSED PER EIA-364-28.

4-3. HUMIDITY: PASSED PER EIA-364-31.

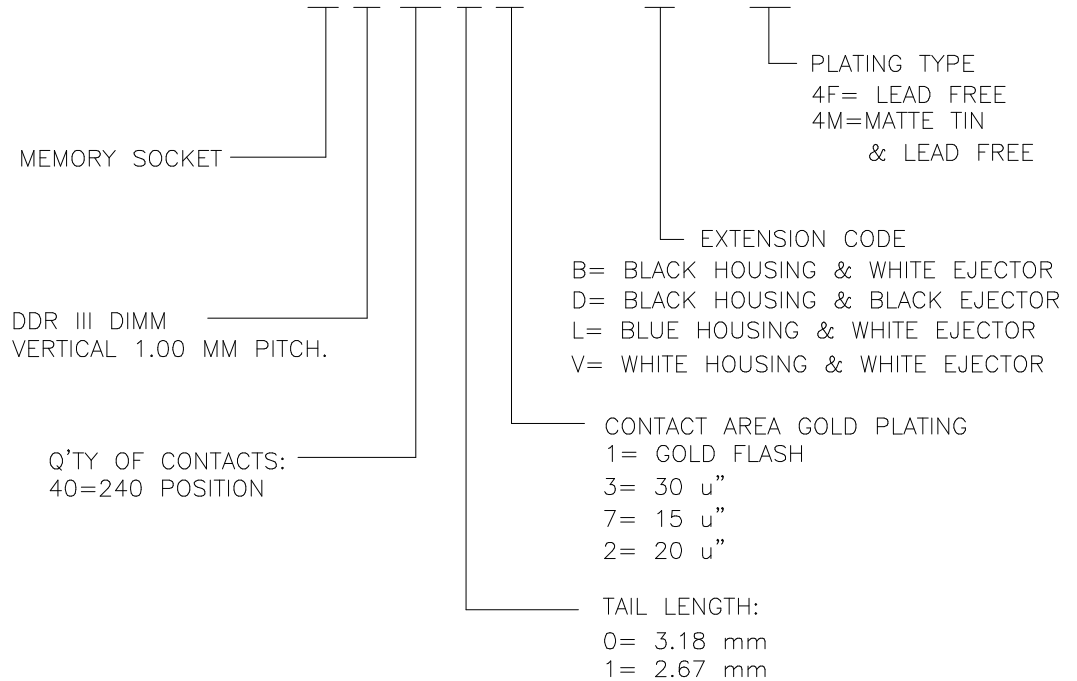
4-4. THERMAL SHOCK: PASSED PER EIA-364-32.

4-5. OPERATING TEMPERATURE: 0°C TO 85°C.

4-6. MECHANICAL SHOCK: PASSED PER EIA-364-27.

# PRODUCT NOMENCLATURE:

PRODUCT NO. : A TH \* \* \* \* - H 9 \* E - 4\*



X.±	X <sup>o</sup> ±	UNITS mm	NAME(INTENDED USE) DDR III DIMM, 240 P 1.00mm PITCH	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED						
.X± 0.25	.X±	MAT'L	PART NO.(INTENDED USE) ATH40*-H9*E-4*	TITLE: CUSTOMER DRAWING						
.XX± 0.15	.XX±	FINISH	APPD: Davy Bu 12/18'13	DWG NO.: 317-0000-2067						
.XXX±	.XXX±	Q'TY	CHKD: Arthur Niu 12/18'13	DR: X.W Wang 12/18'13						
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SCALE	SHEET	REV.								
N/A	4/4	A								